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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	20
Program Memory Size	3KB (2K x 12)
Program Memory Type	ОТР
EEPROM Size	-
RAM Size	72 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6.25V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c57-lp-ss

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

NOTES:

NOTES:



FIGURE 3-1: PIC16C5X SERIES BLOCK DIAGRAM

6.2.2 SPECIAL FUNCTION REGISTERS

The Special Function Registers are registers used by the CPU and peripheral functions to control the operation of the device (Table 6-1).

The Special Registers can be classified into two sets. The Special Function Registers associated with the "core" functions are described in this section. Those related to the operation of the peripheral features are described in the section for each peripheral feature.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Details on Page
N/A	TRIS	I/O Cont	rol Regis	ters (TRIS	SA, TRIS	B, TRISC	:)			1111 1111	35
N/A	OPTION	Contains	s control b	oits to cor	figure Ti	mer0 and	Timer0/V	VDT pres	caler	11 1111	30
00h	INDF	Uses co	Uses contents of FSR to address data memory (not a physical register)						XXXX XXXX	32	
01h	TMR0	Timer0	Timer0 Module Register							XXXX XXXX	38
02h ⁽¹⁾	PCL	Low ord	Low order 8 bits of PC							1111 1111	31
03h	STATUS	PA2	PA1	PA0	TO	PD	Z	DC	С	0001 1xxx	29
04h	FSR	Indirect	Indirect data memory address pointer								32
05h	PORTA	—	—	—	—	RA3	RA2	RA1	RA0	xxxx	35
06h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	XXXX XXXX	35
07h ⁽²⁾	PORTC	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	XXXX XXXX	35

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0' (if applicable). Shaded cells = unimplemented or unused

Note 1: The upper byte of the Program Counter is not directly accessible. See Section 6.5 for an explanation of how to access these bits.

2: File address 07h is a General Purpose Register on the PIC16C54, PIC16CR54, PIC16C56, PIC16CR56, PIC16CR58 and PIC16CR58.

3: These values are valid for PIC16C57/CR57/C58/CR58. For the PIC16C54/CR54/C55/C56/CR56, the value on RESET is 111x xxxx and for MCLR and WDT Reset, the value is 111u uuuu.

6.5.1 PAGING CONSIDERATIONS – PIC16C56/CR56, PIC16C57/CR57 AND PIC16C58/CR58

If the Program Counter is pointing to the last address of a selected memory page, when it increments it will cause the program to continue in the next higher page. However, the page preselect bits in the STATUS Register will not be updated. Therefore, the next GOTO, CALL or modify PCL instruction will send the program to the page specified by the page preselect bits (PA0 or PA<1:0>).

For example, a NOP at location 1FFh (page 0) increments the PC to 200h (page 1). A GOTO xxx at 200h will return the program to address xxh on page 0 (assuming that PA<1:0> are clear).

To prevent this, the page preselect bits must be updated under program control.

6.5.2 EFFECTS OF RESET

The Program Counter is set upon a RESET, which means that the PC addresses the last location in the last page (i.e., the RESET vector).

The STATUS Register page preselect bits are cleared upon a RESET, which means that page 0 is pre-selected.

Therefore, upon a RESET, a GOTO instruction at the RESET vector location will automatically cause the program to jump to page 0.

6.6 Stack

PIC16C5X devices have a 10-bit or 11-bit wide, two-level hardware push/pop stack.

A CALL instruction will push the current value of stack 1 into stack 2 and then push the current program counter value, incremented by one, into stack level 1. If more than two sequential CALL's are executed, only the most recent two return addresses are stored.

A RETLW instruction will pop the contents of stack level 1 into the program counter and then copy stack level 2 contents into level 1. If more than two sequential RETLW's are executed, the stack will be filled with the address previously stored in level 2. Note that the W Register will be loaded with the literal value specified in the instruction. This is particularly useful for the implementation of data look-up tables within the program memory.

For the RETLW instruction, the PC is loaded with the Top of Stack (TOS) contents. All of the devices covered in this data sheet have a two-level stack. The stack has the same bit width as the device PC, therefore, paging is not an issue when returning from a subroutine.

6.7 Indirect Data Addressing; INDF and FSR Registers

The INDF Register is not a physical register. Addressing INDF actually addresses the register whose address is contained in the FSR Register (FSR is a *pointer*). This is indirect addressing.

EXAMPLE 6-1: INDIRECT ADDRESSING

- Register file 08 contains the value 10h
- Register file 09 contains the value 0Ah
- Load the value 08 into the FSR Register
- A read of the INDF Register will return the value of 10h
- Increment the value of the FSR Register by one (FSR = 09h)
- A read of the INDF register now will return the value of 0Ah.

Reading INDF itself indirectly (FSR = 0) will produce 00h. Writing to the INDF Register indirectly results in a no-operation (although STATUS bits may be affected).

A simple program to clear RAM locations 10h-1Fh using indirect addressing is shown in Example 6-2.

EXAMPLE 6-2:

HOW TO CLEAR RAM USING INDIRECT ADDRESSING

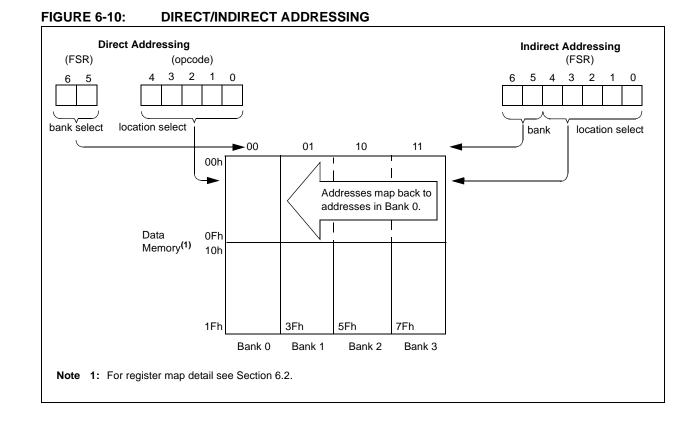
	MOVLW	H'10'	;initialize pointer
	MOVWF	FSR	; to RAM
NEXT	CLRF	INDF	;clear INDF Register
	INCF	FSR,F	;inc pointer
	BTFSC	FSR,4	;all done?
	GOTO	NEXT	;NO, clear next
CONTINUE			
	:		;YES, continue

The FSR is either a 5-bit (PIC16C54, PIC16CR54, PIC16C55, PIC16C56, PIC16CR56) or 7-bit (PIC16C57, PIC16CR57, PIC16CR58, PIC16CR58) wide register. It is used in conjunction with the INDF Register to indirectly address the data memory area.

The FSR<4:0> bits are used to select data memory addresses 00h to 1Fh.

PIC16C54, PIC16CR54, PIC16C55, PIC16C56, PIC16CR56: These do not use banking. FSR<6:5> bits are unimplemented and read as '1's.

PIC16C57, **PIC16CR57**, **PIC16C58**, **PIC16CR58**: FSR<6:5> are the bank select bits and are used to select the bank to be addressed (00 = bank 0, 01 = bank 1, 10 = bank 2, 11 = bank 3).



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10.0 INSTRUCTION SET SUMMARY

Each PIC16C5X instruction is a 12-bit word divided into an OPCODE, which specifies the instruction type and one or more operands which further specify the operation of the instruction. The PIC16C5X instruction set summary in Table 10-2 groups the instructions into byte-oriented, bit-oriented, and literal and control operations. Table 10-1 shows the opcode field descriptions.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator is used to specify which one of the 32 file registers in that bank is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the number of the file in which the bit is located.

For **literal and control** operations, 'k' represents an 8 or 9-bit constant or literal value.

TABLE 10-1:	OPCODE FIELD
	DESCRIPTIONS

DESCRIPTIONS					
Field	Description				
f	Register file address (0x00 to 0x1F)				
W	Working register (accumulator)				
b	Bit address within an 8-bit file register				
k	Literal field, constant data or label				
x	Don't care location (= 0 or 1) The assembler will generate code with $x = 0$. It is the recommended form of use for com-				
	patibility with all Microchip software tools.				
d	Destination select; d = 0 (store result in W) d = 1 (store result in file register 'f') Default is d = 1				
label	Label name				
TOS	Top of Stack				
PC	Program Counter				
WDT	Watchdog Timer Counter				
TO	Time-out bit				
PD	Power-down bit				
dest	Destination, either the W register or the specified register file location				
[]	Options				
()	Contents				
\rightarrow	Assigned to				
< >	Register bit field				
∈	In the set of				
italics	User defined term (font is courier)				

All instructions are executed within one single instruction cycle, unless a conditional test is true or the program counter is changed as a result of an instruction. In this case, the execution takes two instruction cycles. One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time would be 1 μ s. If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time would be 2 μ s.

Figure 10-1 shows the three general formats that the instructions can have. All examples in the figure use the following format to represent a hexadecimal number:

0xhhh

where 'h' signifies a hexadecimal digit.

FIGURE 10-1: GENERAL FORMAT FOR INSTRUCTIONS

Byte-oriented file register operations							
<u>11 6</u>	5	4 0					
OPCODE	d	f (FILE #)					
d = 0 for destination d = 1 for destination f = 5-bit file register	on f						
Bit-oriented file registe	r ope	erations					
11 8	7	5 4 0					
OPCODE	b (Bl	IT #) f (FILE #)					
f = 5-bit file register addressLiteral and control operations (except GOTO)							
11	8	7 0					
OPCODE		k (literal)					
k = 8-bit immediate value							
Literal and control operations - GOTO instruction							
11	9	8 0					
OPCODE		k (literal)					
k = 9-bit immediate value							

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11.8 MPLAB ICD In-Circuit Debugger

Microchip's In-Circuit Debugger, MPLAB ICD, is a powerful, low cost, run-time development tool. This tool is based on the FLASH PIC MCUs and can be used to develop for this and other PIC microcontrollers. The MPLAB ICD utilizes the in-circuit debugging capability built into the FLASH devices. This feature, along with Microchip's In-Circuit Serial ProgrammingTM protocol, offers cost-effective in-circuit FLASH debugging from the graphical user interface of the MPLAB Integrated Development Environment. This enables a designer to develop and debug source code by watching variables, single-stepping and setting break points. Running at full speed enables testing hardware in real-time.

11.9 PRO MATE II Universal Device Programmer

The PRO MATE II universal device programmer is a full-featured programmer, capable of operating in Stand-alone mode, as well as PC-hosted mode. The PRO MATE II device programmer is CE compliant.

The PRO MATE II device programmer has programmable VDD and VPP supplies, which allow it to verify programmed memory at VDD min and VDD max for maximum reliability. It has an LCD display for instructions and error messages, keys to enter commands and a modular detachable socket assembly to support various package types. In Stand-alone mode, the PRO MATE II device programmer can read, verify, or program PIC devices. It can also set code protection in this mode.

11.10 PICSTART Plus Entry Level Development Programmer

The PICSTART Plus development programmer is an easy-to-use, low cost, prototype programmer. It connects to the PC via a COM (RS-232) port. MPLAB Integrated Development Environment software makes using the programmer simple and efficient.

The PICSTART Plus development programmer supports all PIC devices with up to 40 pins. Larger pin count devices, such as the PIC16C92X and PIC17C76X, may be supported with an adapter socket. The PICSTART Plus development programmer is CE compliant.

11.11 PICDEM 1 Low Cost PIC MCU Demonstration Board

The PICDEM 1 demonstration board is a simple board which demonstrates the capabilities of several of Microchip's microcontrollers. The microcontrollers supported are: PIC16C5X (PIC16C54 to PIC16C58A). PIC16C61, PIC16C62X, PIC16C71, PIC16C8X, PIC17C42, PIC17C43 and PIC17C44. All necessary hardware and software is included to run basic demo programs. The user can program the sample microcontrollers provided with the PICDEM 1 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer, and easily test firmware. The user can also connect the PICDEM 1 demonstration board to the MPLAB ICE incircuit emulator and download the firmware to the emulator for testing. A prototype area is available for the user to build some additional hardware and connect it to the microcontroller socket(s). Some of the features include an RS-232 interface, a potentiometer for simulated analog input, push button switches and eight LEDs connected to PORTB.

11.12 PICDEM 2 Low Cost PIC16CXX Demonstration Board

The PICDEM 2 demonstration board is a simple demonstration board that supports the PIC16C62, PIC16C64, PIC16C65, PIC16C73 and PIC16C74 microcontrollers. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM 2 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer, and easily test firmware. The MPLAB ICE in-circuit emulator may also be used with the PICDEM 2 demonstration board to test firmware. A prototype area has been provided to the user for adding additional hardware and connecting it to the microcontroller socket(s). Some of the features include a RS-232 interface, push button switches, a potentiometer for simulated analog input, a serial EEPROM to demonstrate usage of the I^2C^{TM} bus and separate headers for connection to an LCD module and a keypad.

13.2 DC Characteristics: PIC16CR54A-04E, 10E, 20E (Extended)

			Standard Operating Conditions (unless otherwise specified Operating Temperature $-40^{\circ}C \le TA \le +125^{\circ}C$ for extended				
Param No.	Symbol	Characteristic	Min	Min Typ† Max Units			Conditions
D001	Vdd	Supply Voltage RC, XT and LP modes HS mode	3.25 4.5		6.0 5.5	V V	
D002	Vdr	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD Start Voltage to ensure Power-on Reset	—	Vss	—	V	See Section 5.1 for details on Power-on Reset
D004	Svdd	VDD Rise Rate to ensure Power- on Reset	0.05*	_		V/ms	See Section 5.1 for details on Power-on Reset
D010	IDD	Supply Current ⁽²⁾ RC ⁽³⁾ and XT modes HS mode HS mode		1.8 4.8 9.0	3.3 10 20	mA mA mA	Fosc = 4.0 MHz, Vdd = 5.5V Fosc = 10 MHz, Vdd = 5.5V Fosc = 16 MHz, Vdd = 5.5V
D020	IPD	Power-down Current ⁽²⁾		5.0 0.8	22 18	μΑ μΑ	VDD = 3.25V, WDT enabled VDD = 3.25V, WDT disabled

These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

- 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
 - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, TOCKI = VDD, MCLR = VDD; WDT enabled/ disabled as specified.
 - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
- 3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in kΩ.

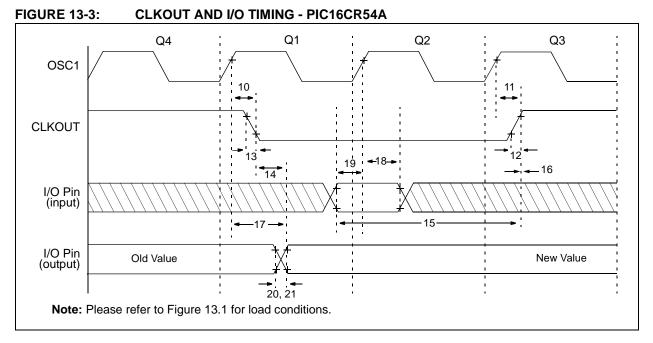


TABLE 13-2: CLKOUT AND I/O TIMING REQUIREMENTS - PIC16CR54A

AC Chara	racteristics Standard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial $-40^{\circ}C \le TA \le +85^{\circ}C$ for industrial $-40^{\circ}C \le TA \le +125^{\circ}C$ for extended					
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units
10	TosH2ckL	OSC1↑ to CLKOUT↓ ⁽¹⁾	—	15	30**	ns
11	TosH2ckH	OSC1↑ to CLKOUT↑ ⁽¹⁾	—	15	30**	ns
12	TckR	CLKOUT rise time ⁽¹⁾	—	5.0	15**	ns
13	TckF	CLKOUT fall time ⁽¹⁾	—	5.0	15**	ns
14	TckL2ioV	CLKOUT↓ to Port out valid ⁽¹⁾	—	—	40**	ns
15	TioV2ckH	Port in valid before CLKOUT ⁽¹⁾	0.25 TCY+30*	—		ns
16	TckH2iol	Port in hold after CLKOUT ⁽¹⁾	0*	—		ns
17	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid ⁽²⁾	—	—	100*	ns
18	TosH2iol	OSC1 [↑] (Q2 cycle) to Port input invalid (I/O in hold time)	TBD	—	—	ns
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	TBD	—	—	ns
20	TioR	Port output rise time ⁽²⁾	_	10	25**	ns
21	TioF	Port output fall time ⁽²⁾	_	10	25**	ns

* These parameters are characterized but not tested.

- ** These parameters are design targets and are not tested. No characterization data available at this time.
- † Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

2: Please refer to Figure 13.1 for load conditions.

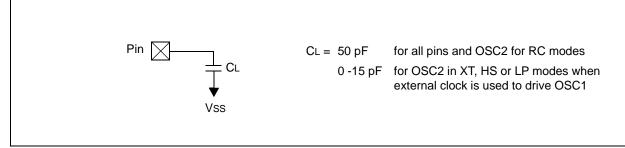
15.5 Timing Parameter Symbology and Load Conditions

The timing parameter symbols have been created with one of the following formats:

1. TppS2ppS

S	
Frequency	T Time
case letters (pp) and their meanings:	
to	mc MCLR
CLKOUT	osc oscillator
cycle time	os OSC1
device reset timer	t0 T0CKI
I/O port	wdt watchdog timer
case letters and their meanings:	
Fall	P Period
High	R Rise
Invalid (Hi-impedance)	V Valid
Low	Z Hi-impedance
	case letters (pp) and their meanings: CLKOUT cycle time device reset timer I/O port case letters and their meanings: Fall High Invalid (Hi-impedance)

FIGURE 15-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS - PIC16C54A



15.6 Timing Diagrams and Specifications

FIGURE 15-2: EXTERNAL CLOCK TIMING - PIC16C54A

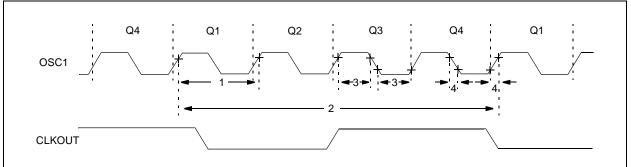


TABLE 15-1: EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16C54A
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$\begin{tabular}{ c c c c c } \hline Standard Operating Conditions (unless otherwise specified) \\ Operating Temperature & 0°C \leq TA \leq +70°C for commercial \\ -40°C \leq TA \leq +85°C for industrial \\ -20°C \leq TA \leq +85°C for industrial - PIC16LV54A-02I \\ -40°C \leq TA \leq +125°C for extended \\ \hline \end{tabular}$						rcial al al - PIC16LV54A-021		
Param No.	Symbol	Characteristic Min Typ† Max Units Conditions						
	Fosc	External CLKIN Fre-	DC	_	4.0	MHz	XT OSC mode	
		quency ⁽¹⁾	DC	—	2.0	MHz	XT osc mode (PIC16LV54A)	
			DC	—	4.0	MHz	HS osc mode (04)	
			DC	—	10	MHz	HS osc mode (10)	
			DC	—	20	MHz	HS osc mode (20)	
			DC	—	200	kHz	LP OSC mode	
		Oscillator Frequency ⁽¹⁾	DC		4.0	MHz	RC osc mode	
			DC	—	2.0	MHz	RC osc mode (PIC16LV54A)	
			0.1	—	4.0	MHz	XT OSC mode	
			0.1	—	2.0	MHz	XT osc mode (PIC16LV54A)	
			4.0	—	4.0	MHz	HS osc mode (04)	
			4.0	—	10	MHz	HS osc mode (10)	
			4.0	—	20	MHz	HS osc mode (20)	
			5.0	—	200	kHz	LP osc mode	

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

- Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.
 - Instruction cycle period (TcY) equals four times the input oscillator time base period.



FIGURE 15-4: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING - PIC16C54A

TABLE 15-3: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER - PIC16C54A

		Standard Operating Condition	ns (unle	ess othe	erwise	specifie	ed)			
AC Characteristics		Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial								
		$-40^{\circ}C \le TA \le +85^{\circ}C$ for industrial $-20^{\circ}C \le TA \le +85^{\circ}C$ for industrial - PIC16LV54A-02I								
Param										
No.	Symbol	Characteristic	Min	Тур†	Мах	Units	Conditions			
30	TmcL	MCLR Pulse Width (low)	100*	_	_	ns	VDD = 5.0V			
			1	—	—	μS	VDD = 5.0V (PIC16LV54A only)			
31	Twdt	Watchdog Timer Time-out	9.0*	18*	30*	ms	VDD = 5.0V (Comm)			
		Period (No Prescaler)								
32	TDRT	Device Reset Timer Period	9.0*	18*	30*	ms	VDD = 5.0V (Comm)			
34	Tioz	I/O Hi-impedance from MCLR	_	_	100*	ns				
		Low	—		1μs	—	(PIC16LV54A only)			

These parameters are characterized but not tested.

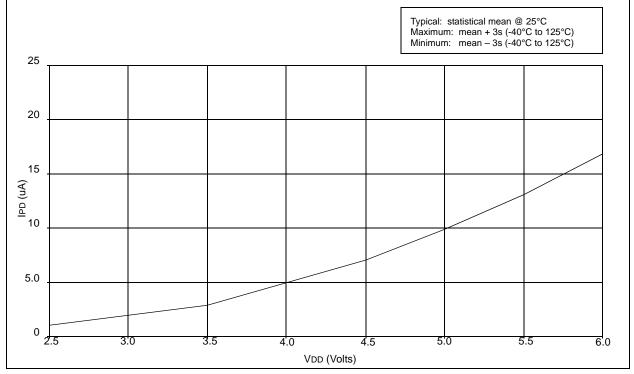
† Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.



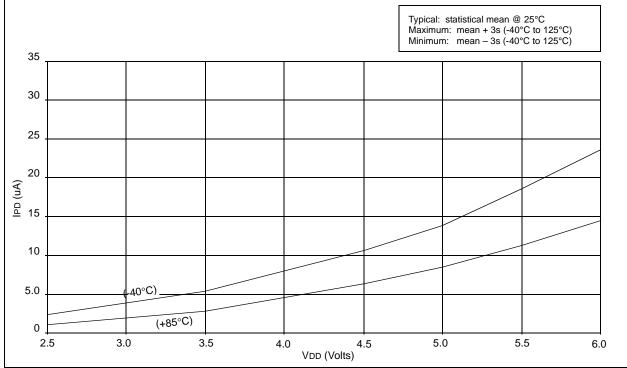
FIGURE 16-17: TRANSCONDUCTANCE (gm) OF HS OSCILLATOR vs. VDD











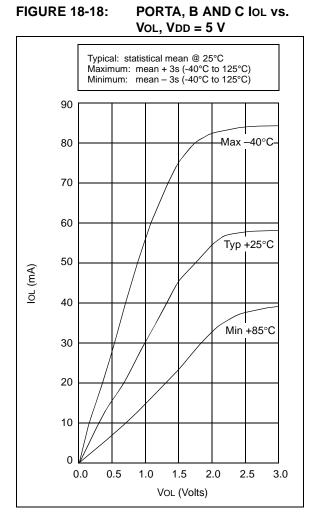


TABLE 18-2:INPUT CAPACITANCE

Pin	Typical Capacitance (pF)				
Pin	18L PDIP	18L SOIC			
RA port	5.0	4.3			
RB port	5.0	4.3			
MCLR	17.0	17.0			
OSC1	4.0	3.5			
OSC2/CLKOUT	4.3	3.5			
тоскі	3.2	2.8			

All capacitance values are typical at 25° C. A part-to-part variation of ±25% (three standard deviations) should be taken into account.

21.0 PACKAGING INFORMATION

21.1 Package Marketing Information

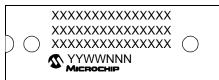
18-Lead PDIP



28-Lead Skinny PDIP (.300")



28-Lead PDIP (.600")



18-Lead SOIC



28-Lead SOIC

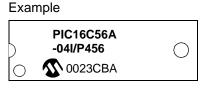


20-Lead SSOP



28-Lead SSOP

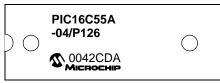




Example



Example



Example



Example



Example



Example



28-Lead Skinny Plastic Dual In-line (SP) - 300 mil (PDIP)





в

		INCHES*		MILLIMETERS			
Dimensi	on Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	р		.100			2.54	
Top to Seating Plane	А	.140	.150	.160	3.56	3.81	4.06
Molded Package Thickness	A2	.125	.130	.135	3.18	3.30	3.43
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.310	.325	7.62	7.87	8.26
Molded Package Width	E1	.275	.285	.295	6.99	7.24	7.49
Overall Length	D	1.345	1.365	1.385	34.16	34.67	35.18
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	С	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.040	.053	.065	1.02	1.33	1.65
Lower Lead Width	В	.016	.019	.022	0.41	0.48	0.56
Overall Row Spacing	èB	.320	.350	.430	8.13	8.89	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter § Significant Characteristic

eВ

Dimension D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed

.010" (0.254mm) per side.

JEDEC Equivalent: MO-095

Drawing No. C04-070

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Notes:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	- <u>xx</u>	Ť	<u>/xx</u>	<u>xxx</u>	Exa	nples	S:
Device	Frequency Range/OSC Type PIC16C54 PIC16C54A PIC16C54C PIC16C55A PIC16C55A PIC16C55A PIC16C56A PIC16C56A PIC16C57C PIC16C57C PIC16C58B PIC16C58B	Temperature Range	$\begin{array}{c} -(2) \\ \lambda_{T}(2) \\ (2) \\ C_{T}(2) \\ C_{T}(2) \\ 2) \\ -(2) \\ -(2) \\ \lambda_{T}(2) \\ 2) \\ -(2) \\ C_{T}(2) \\ C_{T}(2) \\ -$	Pattern	a) b) c) d) Note	 PIC16C55A - 04/P 301 = Commercial Temp., PDIP package, 4 MHz, standard VDD limits, QTP pattern #301 PIC16LC54C - 04I/SO Industrial Temp., SOIC package, 200 kHz, extended VDD limits PIC16C57 - RC/SP = RC Oscillator, commer- cial temp, skinny PDIP package, 4 MHz, stan- dard VDD limits PIC16C58BT -40/SS 123 = commercial temp, SSOP package in tape and reel, 4 MHz, extended VDD limits, ROM pattern #123 1: C = normal voltage range LC = extended 	
Frequency Range/ Oscillator Type	04 200 KHz (LI 10 10 MHz (HS 20 20 MHz (HS 40 40 MHz (HS b ⁽⁴⁾ No oscillato *RC/LP/XT/HS a -02 is available for -04/10/20 options	Crystal ystal/Resonator Crystal P) or 2 MHz (XT an P) or 4 MHz (XT an conly) conly) conly) r type for JW packa re for 16C54/55/56/	nd RC) ages ⁽³⁾ /57 devices on all other device	S		3:	T = in tape and reel - SOIC and SSOP packages only JW Devices are UV erasable and can be programmed to any device configura- tion. JW Devices meet the electrical requirements of each oscillator type, including LC devices. b = Blank
Temperature Range	$b^{(4)} = 0^{\circ}C$ $I = -40^{\circ}C$ $E = -40^{\circ}C$	to +85°C					
Package	JW = 28-pin DIP ⁽³⁾ P = 28-pin SO = 300 m SS = 209 m SP = 28-pin	Waffle Pack 600 mil/18-pin 300 il SOIC il SSOP 300 mil Skinny PD for additional packa	0 mil PDIP DIP				
Pattern		I code (factory spe lank for OTP and W					

Sales and Support

Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office

2. The Microchip Worldwide Site (www.microchip.com)